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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN THE MATTER OF:

KATAYAMA, et al

DOCKET NO: MM4648

FILED: February 9, 2004

GROUP ART UNIT:

SERIAL NO. 10/775,474

EXAMINER:

FOR: CONNECTING STRUCTURE FOR A THERMOPLASTIC TUBE, INTEGRATED ASSEMBLY AND METHOD

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

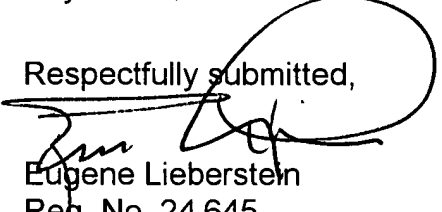
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S I R:

This Information Disclosure Statement is being filed in accordance with the provisions of 37 CFR 1.97 before the issuance of a first Office Action. Any necessary fee should be deducted from Deposit Account No. 01-1944.

This Information Disclosure Statement is being filed to officially make of record the references cited in the attached PTO Form 1449. Copies of these references are also enclosed and it is respectfully requested that they be entered in the record.

Respectfully submitted,


Eugene Lieberstein
Reg. No. 24,645

MAILING CERTIFICATE

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed: Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on March 25, 2005.

Signed: 

Dated: 23 Mar 05

INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>	Docket Number (Optional) MM4648	Application Number 10/775,474
	Applicant(s) Katayama et al	
	Filing Date February 9, 2004	Group Art Unit

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO
		DE 197 35 261 C 1	8/14/97	Germany				
		EP 1 240 981 A2	9/18/02	EP				

OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, Etc.)*

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.